CLAIMS

1. A thermosetting resin composition comprising:

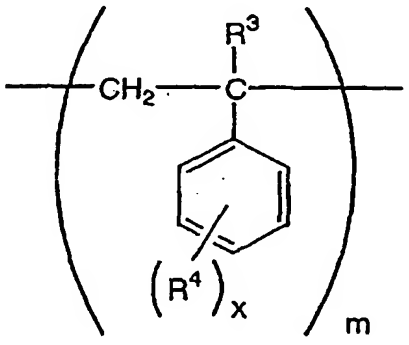
(1) a metal salt of a disubstituted phosphinic acid, and

(2) a resin having a dielectric constant of 2.9 or less at a frequency of 1 GHz or more.

2. The thermosetting rein composition according to claim 1, wherein the dielectric constant of the thermosetting resin composition is 3.0 or less at a frequency of 1 GHz or more.

3. The thermosetting resin composition according to claim 1 or 2, which further comprises (3) a thermosetting nitrogen atom-containing resin.

4. The thermosetting resin composition according to any one of claims 1 to 3, wherein the component (2) is at least one resin compositions selected from the group consisting of:
copolymer resin (2-1) comprising:
monomer unit (a) represented by formula (II):

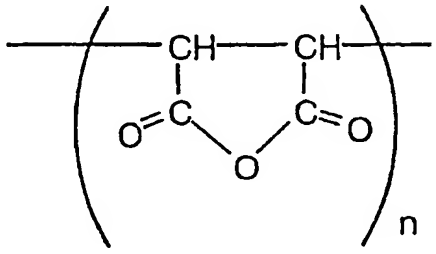


(II)

wherein R^3 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R^4s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; x is an integer of 0 to 3; and

m is a natural number representing the repeating number of a monomer unit in a copolymer, and

monomer unit (b) represented by formula (III):

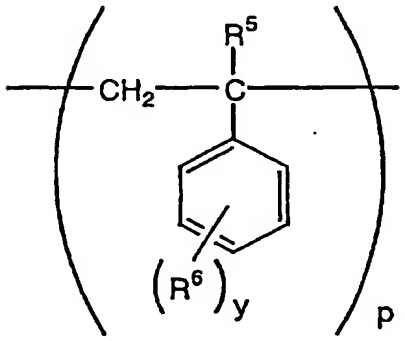


(III)

wherein n is a natural number representing the repeating number of a monomer unit in a copolymer;

copolymer resin (2-2) comprising:

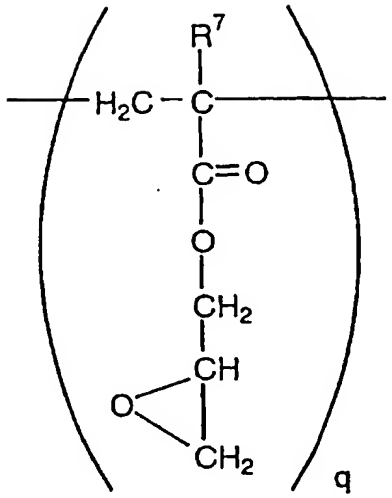
monomer unit (c) represented by formula (IV):



(IV)

wherein R^5 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R^6s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; y is an integer of 0 to 3; and p is a natural number represnting the repeating number of a monomer unit in a copolymer, and

monomer unit (d) represented by formula (V):

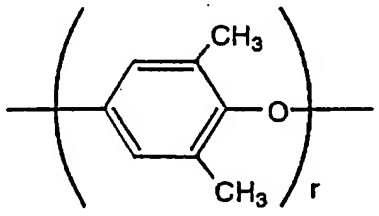


(V)

wherein R^7 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; and q is a natural number representing the repeating number of a monomer unit in a copolymer; and

resin (2-3) comprising:

monomer unit (e) represented by formula (VI):

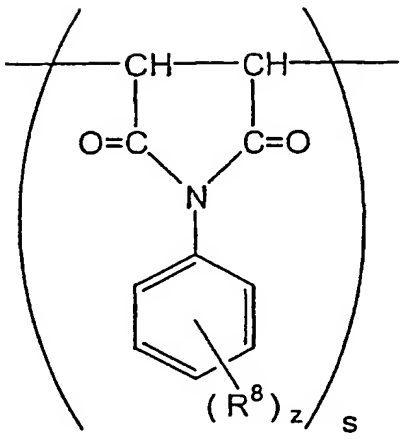


(VI)

wherein r is a natural number representing the repeating number of a monomer unit in a copolymer.

5. The thermosetting resin composition according to claim 4, wherein the copolymer resin (2-1) is a copolymer resin further comprising:

monomer unit (f) represented by the following formula (VII):



(VII)

wherein R^8 is a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group, a hydroxyl group, a thiol group or a carboxyl group; z is an integer of 0 to 3; and s is a natural number representing the repeating number of a monomer unit in a copolymer.

6. The thermosetting resin composition according to any one of claims 1 to 5, which further comprises (4) an epoxy resin.

7. A prepreg using the thermosetting resin composition according to any one of claims 1 to 6.

8. A laminated board obtained by using and laminate molding the prepreg according to claim 7.

9. A thermosetting resin composition comprising a metal salt of a disubstituted phosphinic acid, wherein a dielectric constant of the composition is 3.0 or less at a frequency of 1 GHz or more.